New Products

Heat radiation adhesive sheet SAFC

Low termal resistance

Heat conductivity 1W/mk
From 10μm thickness available

High heat radiativity

Thermal emittance 0.91

Elasticity

Low elasticity
Expected for Stress relief

❖ Heat resistance

Adhesive grade	SAFC		General
Heat conductivity	1W/mk		0.3W/mk
Thickness	10μm	35μm	10μm
Heat resistance	0.016℃･int²/W	0.054℃･int²/W	0.052℃･int²/W

➢ By increasing heat conductivety, flexibility of thickness design can be improved.

❖ Heat radiativity

◆ Thermal emittance(ε)

Materials	Thermal emittance	Heat conductivity (W/mk)
SAFC	0.91	1.0
Alminum*	0.04	235
Copper*	0.07	400

*No surface oxidization

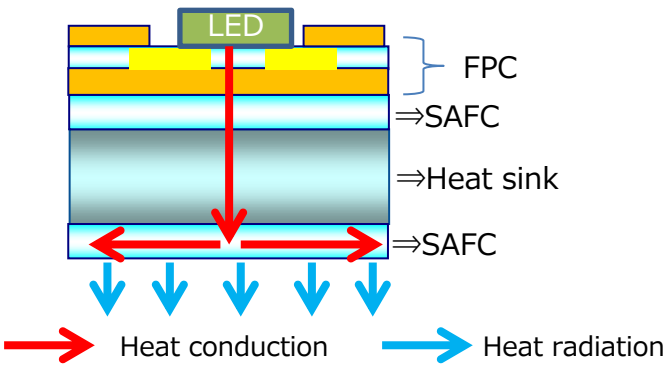

Figure: Heat flow image

➢ By thermal radiation effect, Heat radiativity can be imploved.

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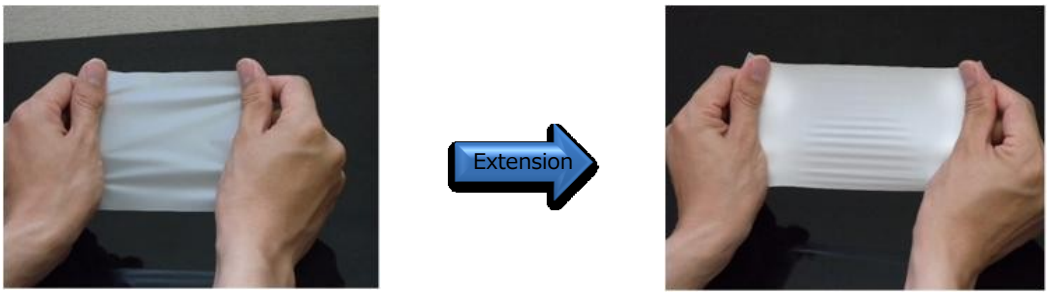
Heat radiation adhesive sheet　SAFC

❖ Elasticity

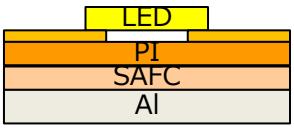
Test item	SAFC
Modurus(GPa)	1.4
Tg（℃）　DMA	19

Elongation of simple adhesive sheet

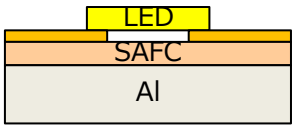


Stress relief effect will be expected, because of excellent elasticity!

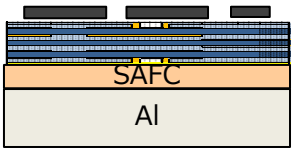
❖ Use cases



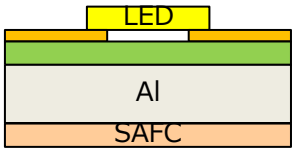
For Thin LED circuit board connection with the heat sink



For insulationlayer of Al circuit board



For conponent mounted board connection with the heat sink



For heat radiation layer of the heat sink

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